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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16c620a-20i-p">https://www.e-xfl.com/product-detail/microchip-technology/pic16c620a-20i-p</a>

# PIC16C62X

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NOTES:

## 2.0 PIC16C62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C62X Product Identification System section at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

### 2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package, is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the Oscillator modes.

Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16C62X.

<b>Note:</b> Microchip does not recommend code protecting windowed devices.
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### 2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications. In addition to the program memory, the configuration bits must also be programmed.

### 2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP programming service for factory production orders. This service is made available for users who chose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices, but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

### 2.4 Serialized Quick-Turnaround-Production<sup>SM</sup> (SQTP<sup>SM</sup>) Devices

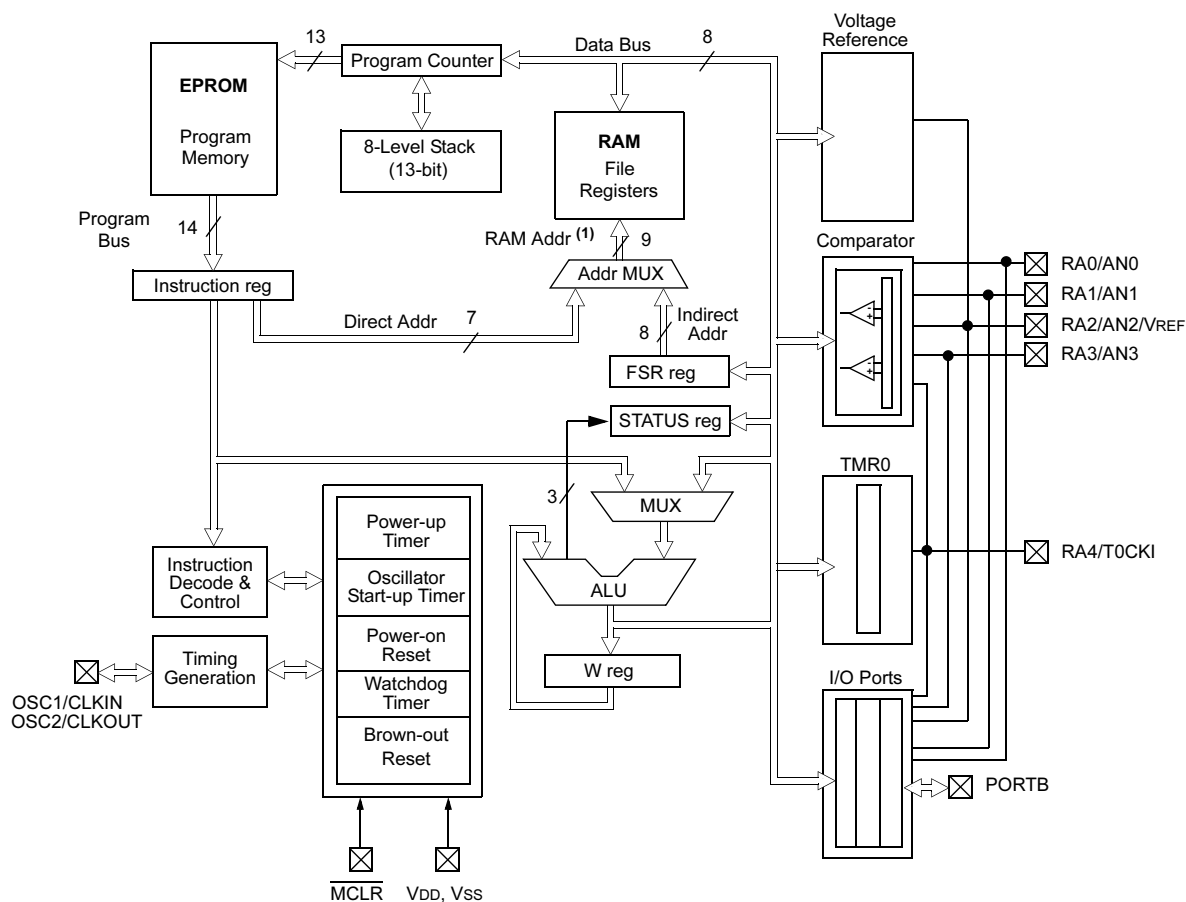
Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number, which can serve as an entry-code, password or ID number.

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**FIGURE 3-1: BLOCK DIAGRAM**

Device	Program Memory	Data Memory (RAM)
PIC16C620	512 x 14	80 x 8
PIC16C620A	512 x 14	96 x 8
PIC16CR620A	512 x 14	96 x 8
PIC16C621	1K x 14	80 x 8
PIC16C621A	1K x 14	96 x 8
PIC16C622	2K x 14	128 x 8
PIC16C622A	2K x 14	128 x 8



**Note 1:** Higher order bits are from the STATUS register.

# PIC16C62X

## 3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

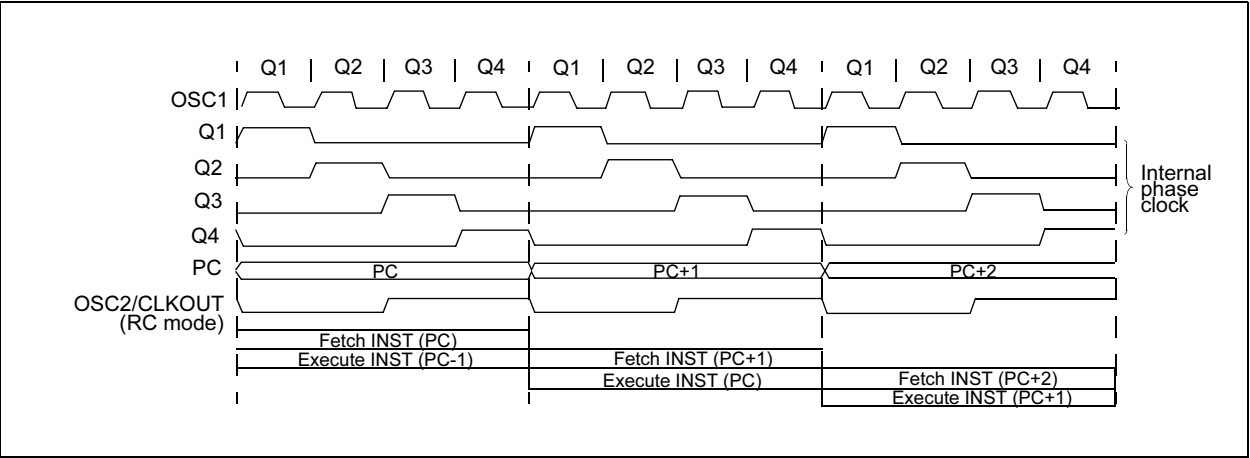
## 3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., GOTO) then two cycles are required to complete the instruction (Example 3-1).

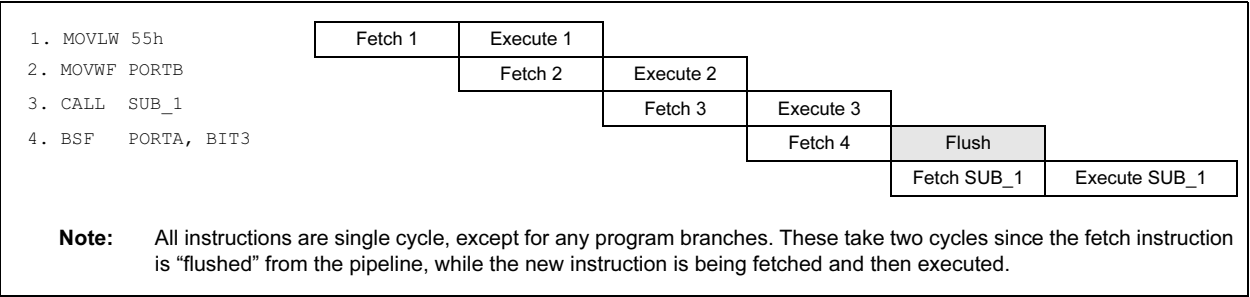
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-2: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



# PIC16C62X

## 4.2.2.1 STATUS Register

The STATUS register, shown in Register 4-1, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the  $\overline{\text{TO}}$  and  $\overline{\text{PD}}$  bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper-three bits and set the Z bit. This leaves the STATUS register as 000uu1uu (where u = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any STATUS bit. For other instructions not affecting any STATUS bits, see the "Instruction Set Summary".

**Note 1:** The IRP and RP1 bits (STATUS<7:6>) are not used by the PIC16C62X and should be programmed as '0'. Use of these bits as general purpose R/W bits is NOT recommended, since this may affect upward compatibility with future products.

**2:** The C and DC bits operate as a Borrow and Digit Borrow out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

### REGISTER 4-1: STATUS REGISTER (ADDRESS 03H OR 83H)

Reserved	Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C
bit 7							bit 0

- bit 7 **IRP:** Register Bank Select bit (used for indirect addressing)  
 1 = Bank 2, 3 (100h - 1FFh)  
 0 = Bank 0, 1 (00h - FFh)  
 The IRP bit is reserved on the PIC16C62X; always maintain this bit clear.
- bit 6-5 **RP<1:0>:** Register Bank Select bits (used for direct addressing)  
 01 = Bank 1 (80h - FFh)  
 00 = Bank 0 (00h - 7Fh)  
 Each bank is 128 bytes. The RP1 bit is reserved on the PIC16C62X; always maintain this bit clear.
- bit 4  **$\overline{\text{TO}}$ :** Time-out bit  
 1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction  
 0 = A WDT time-out occurred
- bit 3  **$\overline{\text{PD}}$ :** Power-down bit  
 1 = After power-up or by the `CLRWDT` instruction  
 0 = By execution of the `SLEEP` instruction
- bit 2 **Z:** Zero bit  
 1 = The result of an arithmetic or logic operation is zero  
 0 = The result of an arithmetic or logic operation is not zero
- bit 1 **DC:** Digit carry/borrow bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(for borrow the polarity is reversed)  
 1 = A carry-out from the 4th low order bit of the result occurred  
 0 = No carry-out from the 4th low order bit of the result
- bit 0 **C:** Carry/borrow bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)  
 1 = A carry-out from the Most Significant bit of the result occurred  
 0 = No carry-out from the Most Significant bit of the result occurred
- Note:** For borrow the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

#### Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared    x = Bit is unknown



**TABLE 5-3: PORTB FUNCTIONS**

Name	Bit #	Buffer Type	Function
RB0/INT	bit0	TTL/ST <sup>(1)</sup>	Input/output or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST <sup>(2)</sup>	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming clock pin.
RB7	bit7	TTL/ST <sup>(2)</sup>	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming data pin.

Legend: ST = Schmitt Trigger, TTL = TTL input

**Note 1:** This buffer is a Schmitt Trigger input when configured as the external interrupt.

**2:** This buffer is a Schmitt Trigger input when used in Serial Programming mode.

**TABLE 5-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
81h	OPTION	RBP <sub>U</sub>	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: u = unchanged, x = unknown

**Note 1:** Shaded bits are not used by PORTB.

## 9.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the PD bit in the STATUS register is cleared, the TO bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSS with no external circuitry drawing current from the I/O pin and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

**Note:** It should be noted that a RESET generated by a WDT time-out does not drive MCLR pin low.

The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The  $\overline{TO}$  and  $\overline{PD}$  bits in the STATUS register can be used to determine the cause of device RESET. PD bit, which is set on power-up, is cleared when SLEEP is invoked.  $\overline{TO}$  bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

**Note:** If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The SLEEP instruction is completely executed.

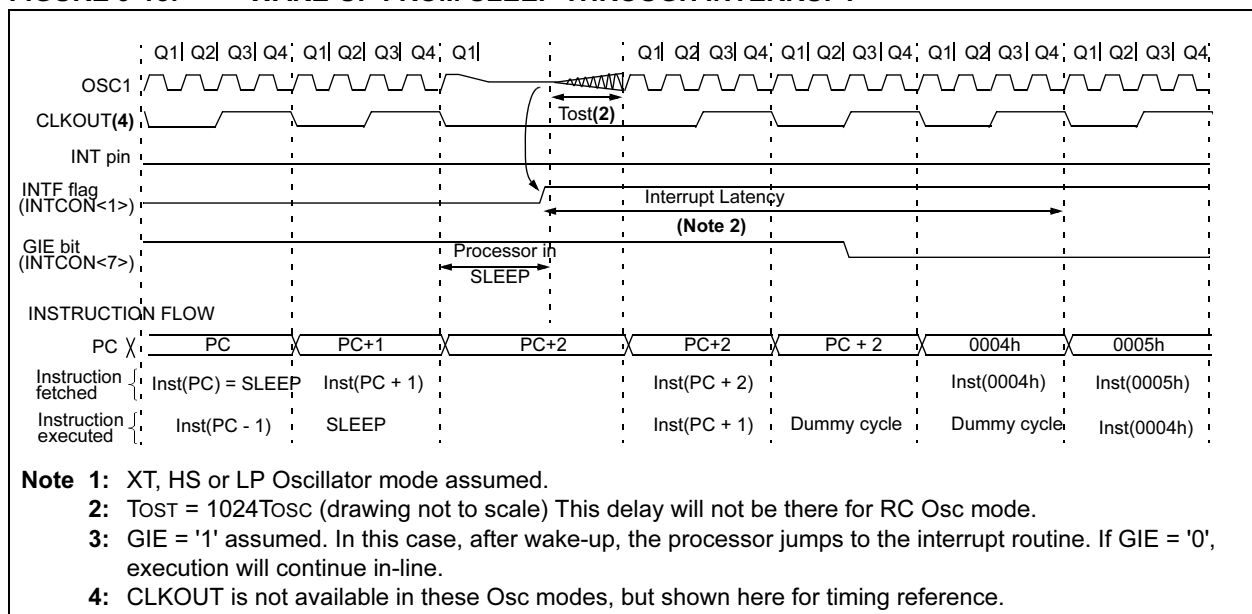
### 9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on MCLR pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

The WDT is cleared when the device wakes up from SLEEP, regardless of the source of wake-up.

**FIGURE 9-18: WAKE-UP FROM SLEEP THROUGH INTERRUPT**



# PIC16C62X

## 9.9 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

**Note:** Microchip does not recommend code protecting windowed devices.

## 9.10 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify. Only the Least Significant 4 bits of the ID locations are used.

## 9.11 In-Circuit Serial Programming™

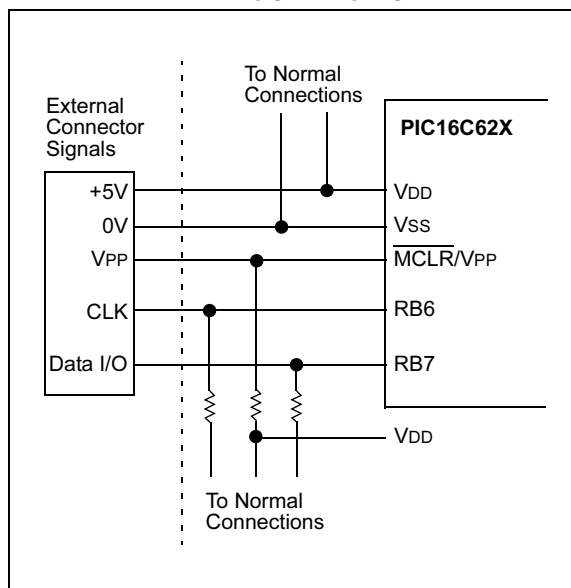
The PIC16C62X microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a Program/Verify mode by holding the RB6 and RB7 pins low, while raising the MCLR (VPP) pin from VIL to VIH (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After RESET, to place the device into Programming/Verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X/9XX Programming Specification (DS30228).

A typical In-Circuit Serial Programming connection is shown in Figure 9-19.

**FIGURE 9-19: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION**



## 10.0 INSTRUCTION SET SUMMARY

Each PIC16C62X instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C62X instruction set summary in Table 10-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

**TABLE 10-1: OPCODE FIELD DESCRIPTIONS**

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination either the W register or the specified register file location
[ ]	Options
( )	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 10-1 lists the instructions recognized by the MPASM™ assembler.

Figure 10-1 shows the three general formats that the instructions can have.

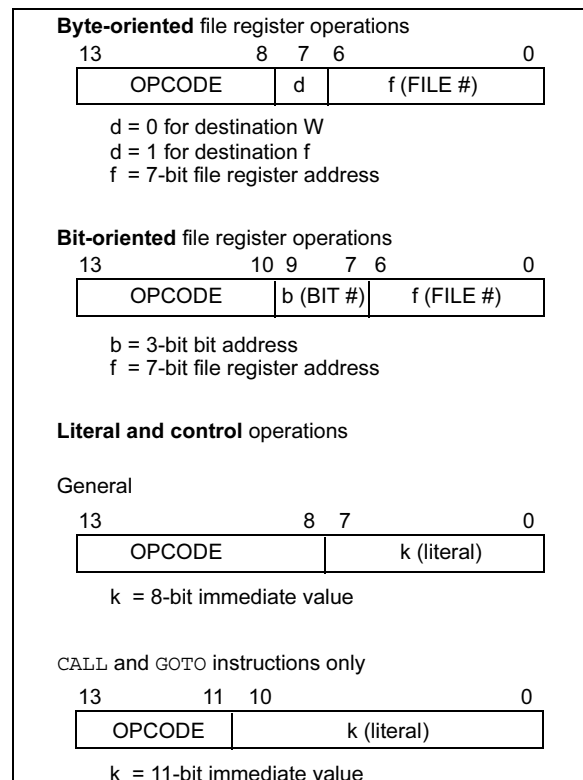
**Note:** To maintain upward compatibility with future PICmicro® products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

**FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS**



MOVF		Move f			
Syntax:	[ <i>label</i> ] MOVF f,d				
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$				
Operation:	(f) $\rightarrow$ (dest)				
Status Affected:	Z				
Encoding:	00	1000	dfff	ffff	
Description:	The contents of register f is moved to a destination dependent upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.				
Words:	1				
Cycles:	1				
Example	MOV FSR, 0				
After Instruction					
	W	=	value in FSR		
	register				
	Z	=	1		

MOVWF		Move W to f			
Syntax:	[ <i>label</i> ] MOVWF f				
Operands:	0 ≤ f ≤ 127				
Operation:	(W) → (f)				
Status Affected:	None				
Encoding:	00	0000	1fff	ffff	
Description:	Move data from W register to register 'f'.				
Words:	1				
Cycles:	1				
Example	MOVWF OPTION				
	Before Instruction				
	OPTION	=	0xFF		
	W	=	0x4F		
	After Instruction				
	OPTION	=	0x4F		
	W	=	0x4F		

NOP	No Operation			
Syntax:	[ <i>label</i> ] NOP			
Operands:	None			
Operation:	No operation			
Status Affected:	None			
Encoding:	00	0000	0xx0	0000
Description:	No operation.			
Words:	1			
Cycles:	1			
Example	NOP			

OPTION	Load Option Register				
Syntax:	[ <i>label</i> ] OPTION				
Operands:	None				
Operation:	(W) → OPTION				
Status Affected:	None				
Encoding:	<table><tr><td>00</td><td>0000</td><td>0110</td><td>0010</td></tr></table>	00	0000	0110	0010
00	0000	0110	0010		
Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.				
Words:	1				
Cycles:	1				
Example	<div><b>To maintain upward compatibility with future PICmicro<sup>®</sup> products, do not use this instruction.</b></div>				

# PIC16C62X

## 12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended)

PIC16C62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage VDD range is the PIC16C62X range.					
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	6.0	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D001	VDD	Supply Voltage	2.5	—	6.0	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D002	VDR	RAM Data Retention Voltage <sup>(1)</sup>	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage <sup>(1)</sup>	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.3	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.3	V	BOREN configuration bit is cleared
D010	IDD	Supply Current <sup>(2)</sup>	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	35	70	μA	FOSC = 32 kHz, VDD = 4.0V, WDT disabled, LP mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled, HS mode
D010	IDD	Supply Current <sup>(2)</sup>	—	1.4	2.5	mA	FOSC = 2.0 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)
			—	26	53	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D020	IPD	Power-down Current <sup>(3)</sup>	—	1.0	2.5	μA	VDD=4.0V, WDT disabled (125°C)
D020	IPD	Power-down Current <sup>(3)</sup>	—	0.7	2	μA	VDD=3.0V, WDT disabled

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** This is the limit to which VDD can be lowered without losing RAM data.

**Note 2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

**Note 3:** The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

**Note 4:** For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula:  $I_r = V_{DD}/2R_{EXT}$  (mA) with REXT in kΩ.

**Note 5:** The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

## 12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended)

<b>PIC16CR62XA-04 PIC16CR62XA-20</b>			<b>Standard Operating Conditions (unless otherwise stated)</b> Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
<b>PIC16LCR62XA-04</b>			<b>Standard Operating Conditions (unless otherwise stated)</b> Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage <sup>(1)</sup>	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage <sup>(1)</sup>	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current <sup>(2)</sup>	—	1.2	1.7	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	500	900	μA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	3.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current <sup>(2)</sup>	—	1.2	1.7	mA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	400	800	μA	FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

## 12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D040	V <sub>IH</sub>	Input High Voltage I/O ports with TTL buffer	2.0V 0.25 V <sub>DD</sub> + 0.8V	—	V <sub>DD</sub> V <sub>DD</sub>	V	V <sub>DD</sub> = 4.5V to 5.5V otherwise  (Note 1)
D041		with Schmitt Trigger input	0.8 V <sub>DD</sub>	—	V <sub>DD</sub>		
D042		MCLR RA4/T0CKI	0.8 V <sub>DD</sub>	—	V <sub>DD</sub>	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 V <sub>DD</sub> 0.9 V <sub>DD</sub>	—	V <sub>DD</sub>	V	
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V <sub>DD</sub> = 5.0V, V <sub>PIN</sub> = V <sub>SS</sub>
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V <sub>DD</sub> = 5.0V, V <sub>PIN</sub> = V <sub>SS</sub>
D060	I <sub>IL</sub>	Input Leakage Current <sup>(2, 3)</sup> I/O ports (Except PORTA)			±1.0	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub>
D063		OSC1, MCLR	—	—	±5.0	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , XT, HS and LP osc configuration
D060	I <sub>IL</sub>	Input Leakage Current <sup>(2, 3)</sup> I/O ports (Except PORTA)			±1.0	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub>
D063		OSC1, MCLR	—	—	±5.0	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , XT, HS and LP osc configuration
D080	V <sub>OL</sub>	Output Low Voltage I/O ports	—	—	0.6	V	I <sub>OL</sub> = 8.5 mA, V <sub>DD</sub> = 4.5V, $-40^{\circ}$ to $+85^{\circ}\text{C}$
			—	—	0.6	V	I <sub>OL</sub> = 7.0 mA, V <sub>DD</sub> = 4.5V, $+125^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I <sub>OL</sub> = 1.6 mA, V <sub>DD</sub> = 4.5V, $-40^{\circ}$ to $+85^{\circ}\text{C}$
			—	—	0.6	V	I <sub>OL</sub> = 1.2 mA, V <sub>DD</sub> = 4.5V, $+125^{\circ}\text{C}$

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

**2:** The leakage current on the MCLR pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

**3:** Negative current is defined as coming out of the pin.

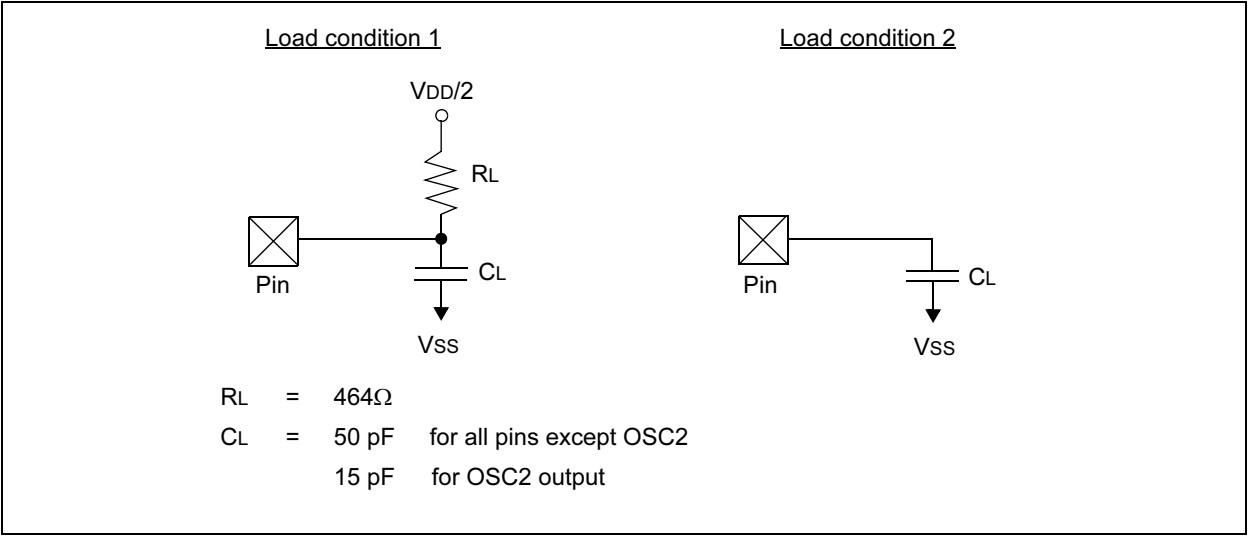
12.8 Timing Parameter Symbolology

The timing parameter symbols have been created with one of the following formats:

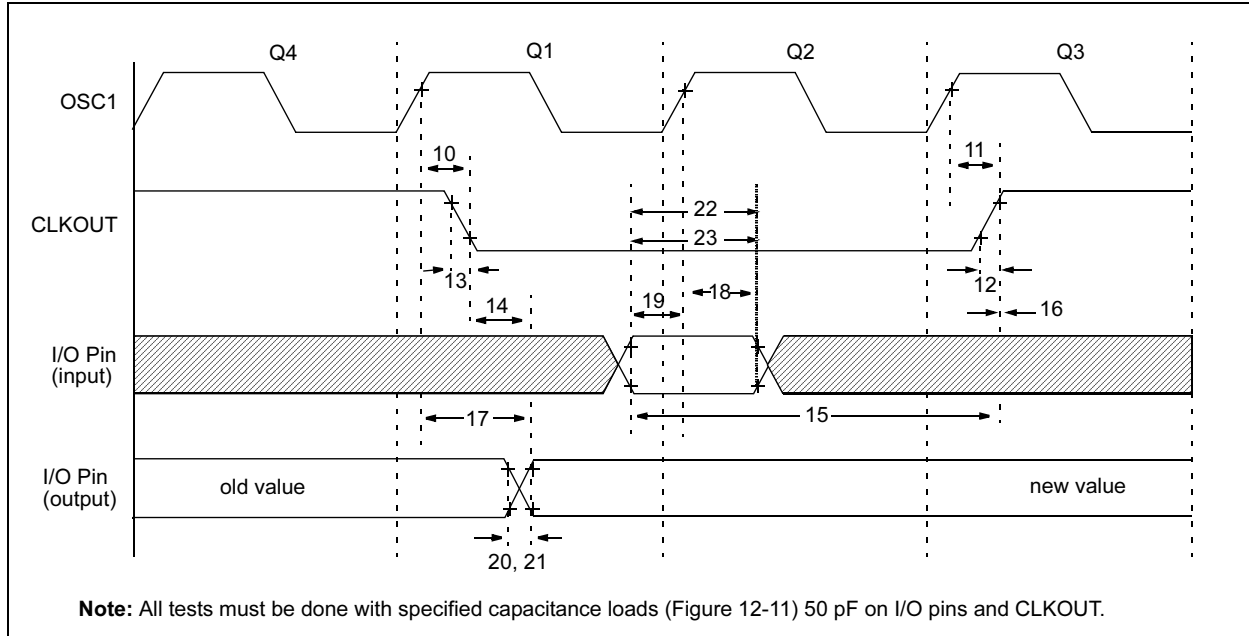
- 1. TppS2ppS
- 2. TppS

<b>T</b>			
F	Frequency	T	Time
Lowercase subscripts (pp) and their meanings:			
<b>pp</b>			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	MCLR		
Uppercase letters and their meanings:			
<b>S</b>			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 12-11: LOAD CONDITIONS



**FIGURE 12-13: CLKOUT AND I/O TIMING**



# PIC16C62X

FIGURE 13-3: I<sub>DD</sub> VS. V<sub>DD</sub> (XT OSC 4 MHZ)

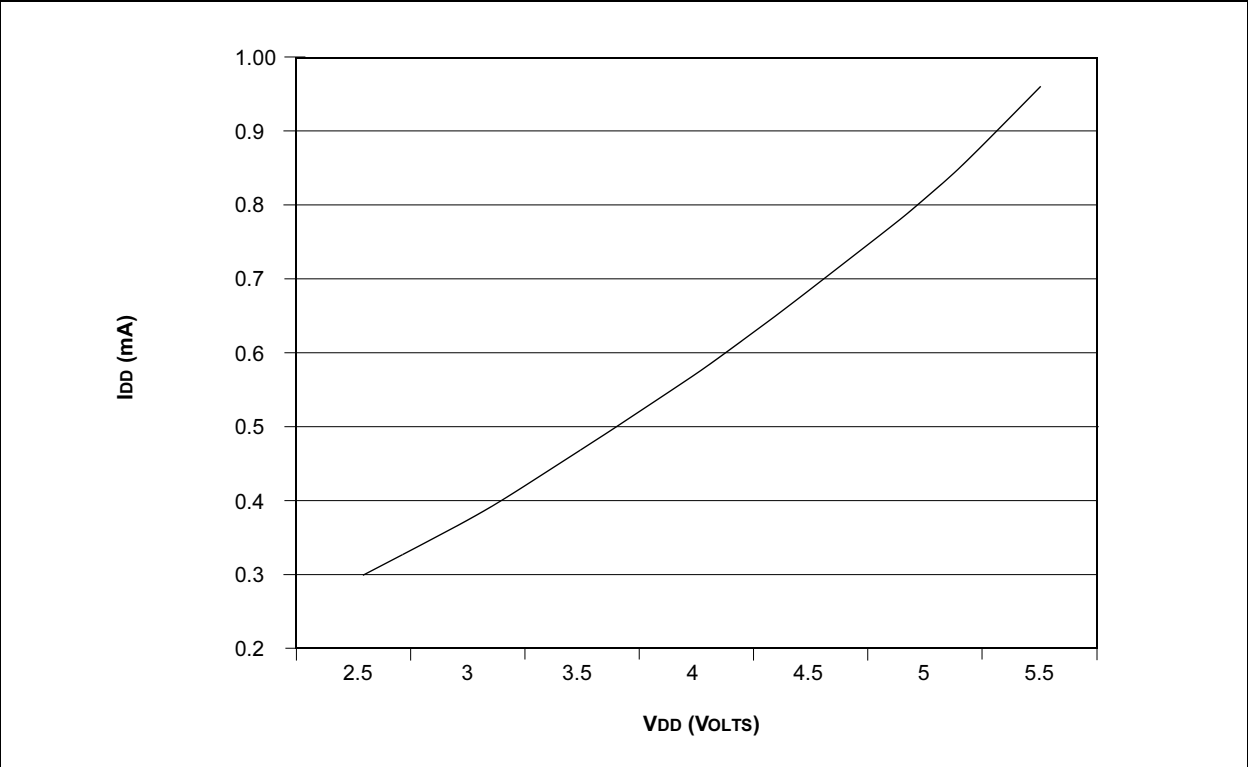


FIGURE 13-4: I<sub>OL</sub> vs. V<sub>OL</sub>, V<sub>DD</sub> = 3.0V)

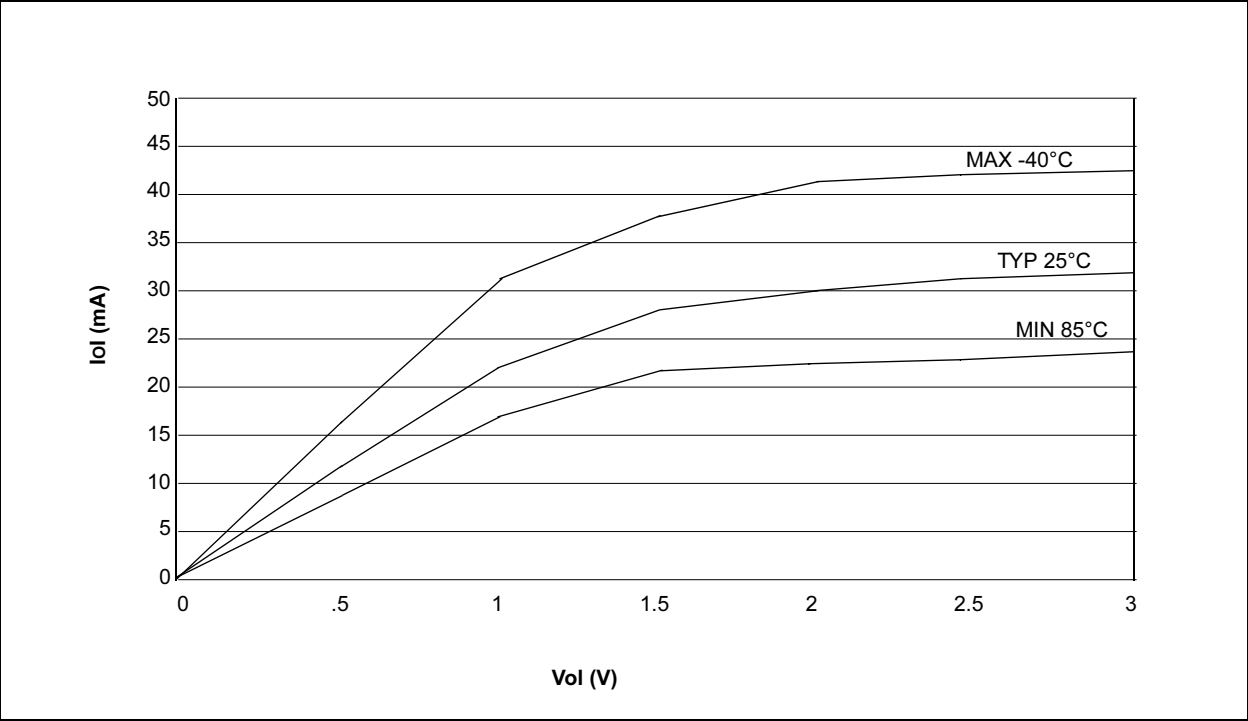


FIGURE 13-5:  $I_{OH}$  vs.  $V_{OH}$ ,  $V_{DD} = 3.0V$

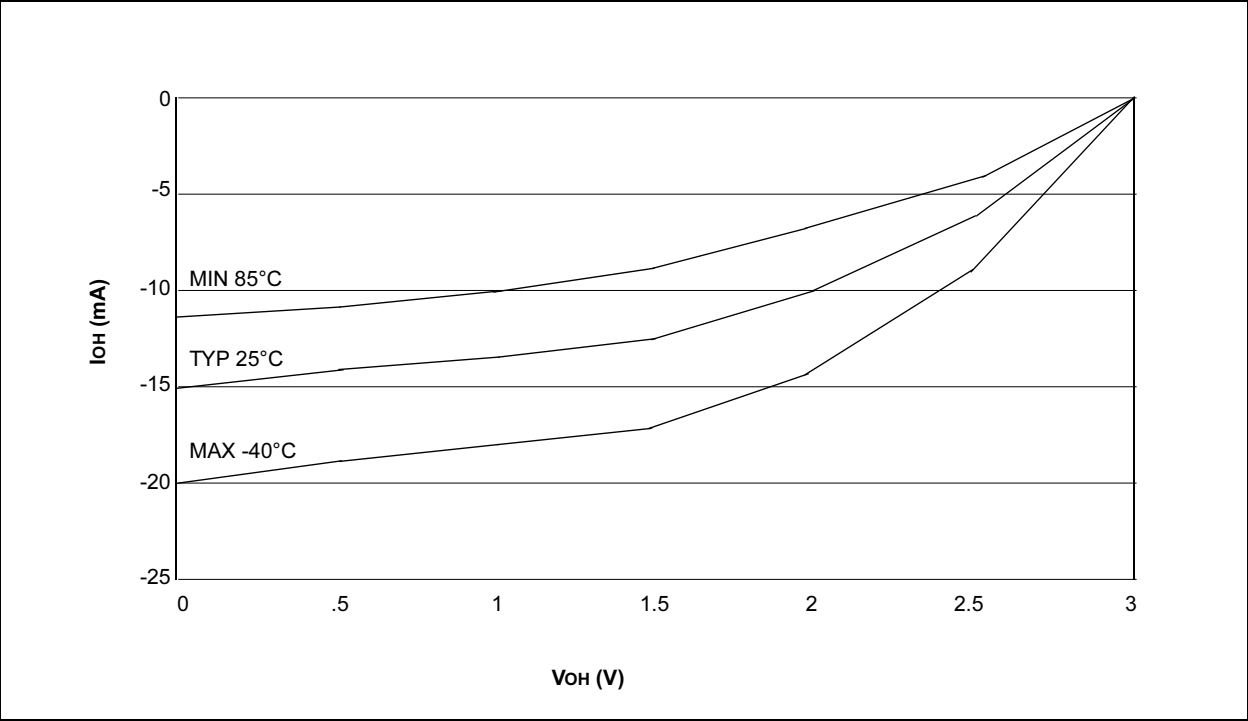
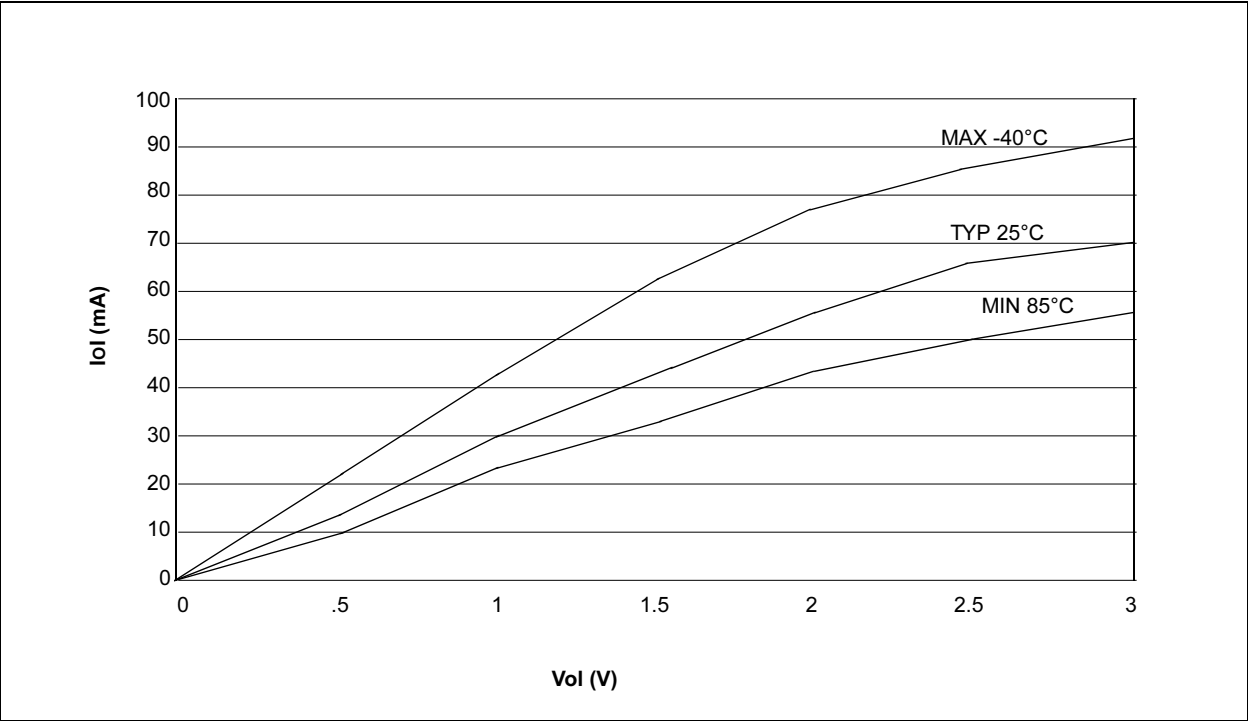
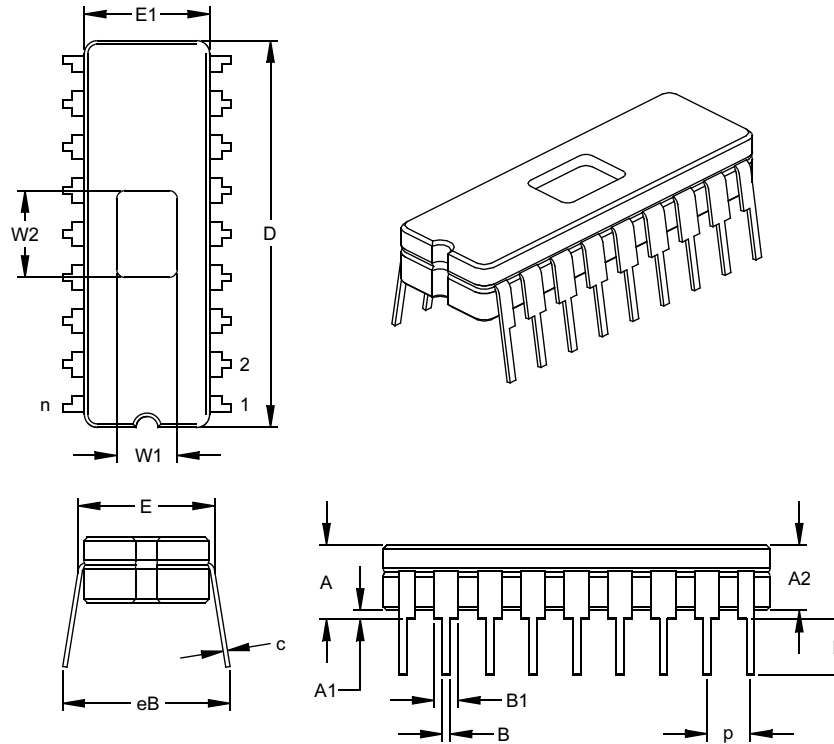


FIGURE 13-6:  $I_{OL}$  vs.  $V_{OL}$ ,  $V_{DD} = 5.5V$



## 14.0 PACKAGING INFORMATION

### 18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	§ eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

\* Controlling Parameter  
 § Significant Characteristic  
 JEDEC Equivalent: MO-036  
 Drawing No. C04-010

## APPENDIX A: ENHANCEMENTS

The following are the list of enhancements over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14 bits. This allows larger page sizes both in program memory (4K now as opposed to 512 before) and register file (up to 128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. PA2, PA1, PA0 bits are removed from STATUS register.
3. Data memory paging is slightly redefined. STATUS register is modified.
4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out, although they are kept for compatibility with PIC16C5X.
5. OPTION and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. RESET vector is changed to 0000h.
9. RESET of all registers is revisited. Five different RESET (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from SLEEP through interrupt is added.
11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt-on-change feature.
13. Timer0 clock input, T0CKI pin is also a port pin (RA4/T0CKI) and has a TRIS bit.
14. FSR is made a full 8-bit register.
15. "In-circuit programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, VPP, RB6 (clock) and RB7 (data in/out).
16. PCON STATUS register is added with a Power-on-Reset (POR) STATUS bit and a Brown-out Reset STATUS bit (BOD).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. PORTA inputs are now Schmitt Trigger inputs.
19. Brown-out Reset reset has been added.
20. Common RAM registers F0h-FFh implemented in bank1.

## APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change RESET vector to 0000h.